

Title (en)
CONTROLLED BUCKLING STRUCTURES IN SEMICONDUCTOR INTERCONNECTS AND NANOMEMBRANES FOR STRETCHABLE ELECTRONICS

Title (de)
GESTEUERTE KNICKSTRUKTUREN IN HALBLEITERVERBINDUNGEN UND NANOMEMBRANEN FÜR DEHNBARE ELEKTRONIKARTIKEL

Title (fr)
STRUCTURES À DÉFORMATION CONTRÔLÉE DANS DES INTERCONNEXIONS DE SEMI-CONDUCTEURS ET DES NANOMEMBRANES POUR DISPOSITIFS ÉLECTRONIQUES ÉTIRABLES

Publication
EP 2064710 A4 20110504 (EN)

Application
EP 07841968 A 20070906

Priority

- US 2007077759 W 20070906
- US 82468306 P 20060906
- US 94462607 P 20070618

Abstract (en)
[origin: WO2008030960A2] In an aspect, the present invention provides stretchable, and optionally printable, components such as semiconductors and electronic circuits capable of providing good performance when stretched, compressed, flexed or otherwise deformed, and related methods of making or tuning such stretchable components. Stretchable semiconductors and electronic circuits preferred for some applications are flexible, in addition to being stretchable, and thus are capable of significant elongation, flexing, bending or other deformation along one or more axes. Further, stretchable semiconductors and electronic circuits of the present invention are adapted to a wide range of device configurations to provide fully flexible electronic and optoelectronic devices.

IPC 8 full level
H01B 7/06 (2006.01); **H01R 35/00** (2006.01)

CPC (source: EP KR)
B81B 3/0078 (2013.01 - EP); **B82Y 10/00** (2013.01 - EP); **H01L 21/185** (2013.01 - KR); **H01L 21/4857** (2013.01 - KR); **H01L 21/6835** (2013.01 - EP); **H01L 21/76832** (2013.01 - KR); **H01L 21/8221** (2013.01 - EP); **H01L 21/8258** (2013.01 - EP KR); **H01L 23/4985** (2013.01 - KR); **H01L 23/5387** (2013.01 - KR); **H01L 27/0605** (2013.01 - EP); **H01L 27/0688** (2013.01 - EP); **H01L 29/0665** (2013.01 - EP); **H01L 29/0673** (2013.01 - EP); **H01L 29/16** (2013.01 - EP); **H01L 29/1602** (2013.01 - EP); **H01L 29/1606** (2013.01 - EP); **H01L 29/20** (2013.01 - EP); **H01L 29/7781** (2013.01 - EP); **H01L 29/7842** (2013.01 - EP); **H05K 1/0283** (2013.01 - EP); **H10K 77/111** (2023.02 - KR); **H01L 27/1292** (2013.01 - EP); **H01L 27/1446** (2013.01 - EP); **H01L 29/78681** (2013.01 - EP); **H01L 29/78696** (2013.01 - EP); **H01L 31/0203** (2013.01 - EP); **H01L 2924/00011** (2013.01 - EP); **H01L 2924/0002** (2013.01 - EP); **H01L 2924/13091** (2013.01 - EP); **H01L 2924/30105** (2013.01 - EP); **H05K 1/0313** (2013.01 - EP); **H05K 3/20** (2013.01 - EP); **H05K 2201/0133** (2013.01 - EP); **H05K 2201/09045** (2013.01 - EP); **H05K 2203/0271** (2013.01 - EP); **H10K 19/201** (2023.02 - EP); **H10K 77/111** (2023.02 - EP); **Y02E 10/549** (2013.01 - EP); **Y02P 70/50** (2015.11 - EP)

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Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC MT NL PL PT RO SE SI SK TR

DOCDB simple family (publication)
WO 2008030960 A2 20080313; WO 2008030960 A3 20080724; CN 101681695 A 20100324; CN 101681695 B 20130410; CN 103213935 A 20130724; CN 103213935 B 20170301; EP 2064710 A2 20090603; EP 2064710 A4 20110504; JP 2010503238 A 20100128; JP 2013239716 A 20131128; JP 2015216365 A 20151203; JP 5578509 B2 20140827; JP 5735585 B2 20150617; KR 101453419 B1 20141023; KR 101612749 B1 20160427; KR 101689747 B1 20161227; KR 101814683 B1 20180105; KR 102087337 B1 20200311; KR 20090086199 A 20090811; KR 20140043244 A 20140408; KR 20150003308 A 20150108; KR 20160140962 A 20161207; KR 20180002083 A 20180105; MY 149475 A 20130830; MY 172115 A 20191114; TW 200836353 A 20080901; TW 201434163 A 20140901; TW 201735380 A 20171001; TW 1485863 B 20150521; TW 1587527 B 20170611; TW 1654770 B 20190321

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